

SOT1848-2

BGA1517, plastic ball grid array package; 1517 balls, 1 mm pitch, 40 mm x 40 mm x 3.36 mm body

18 December 2017

Package information

1. Package summary

Terminal position code	B (bottom)
Package type descriptive code	BGA1517
Package style descriptive code	BGA (ball grid array)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	18-12-2017
Manufacturer package code	98ASA01023D

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	-	-	40	-	mm
E	package width	-	-	40	-	mm
A ₂	package height	-	-	3.36	-	mm
e	nominal pitch	-	-	1	-	mm
n ₂	actual quantity of termination	-	-	1517	-	A/A



2. Package outline

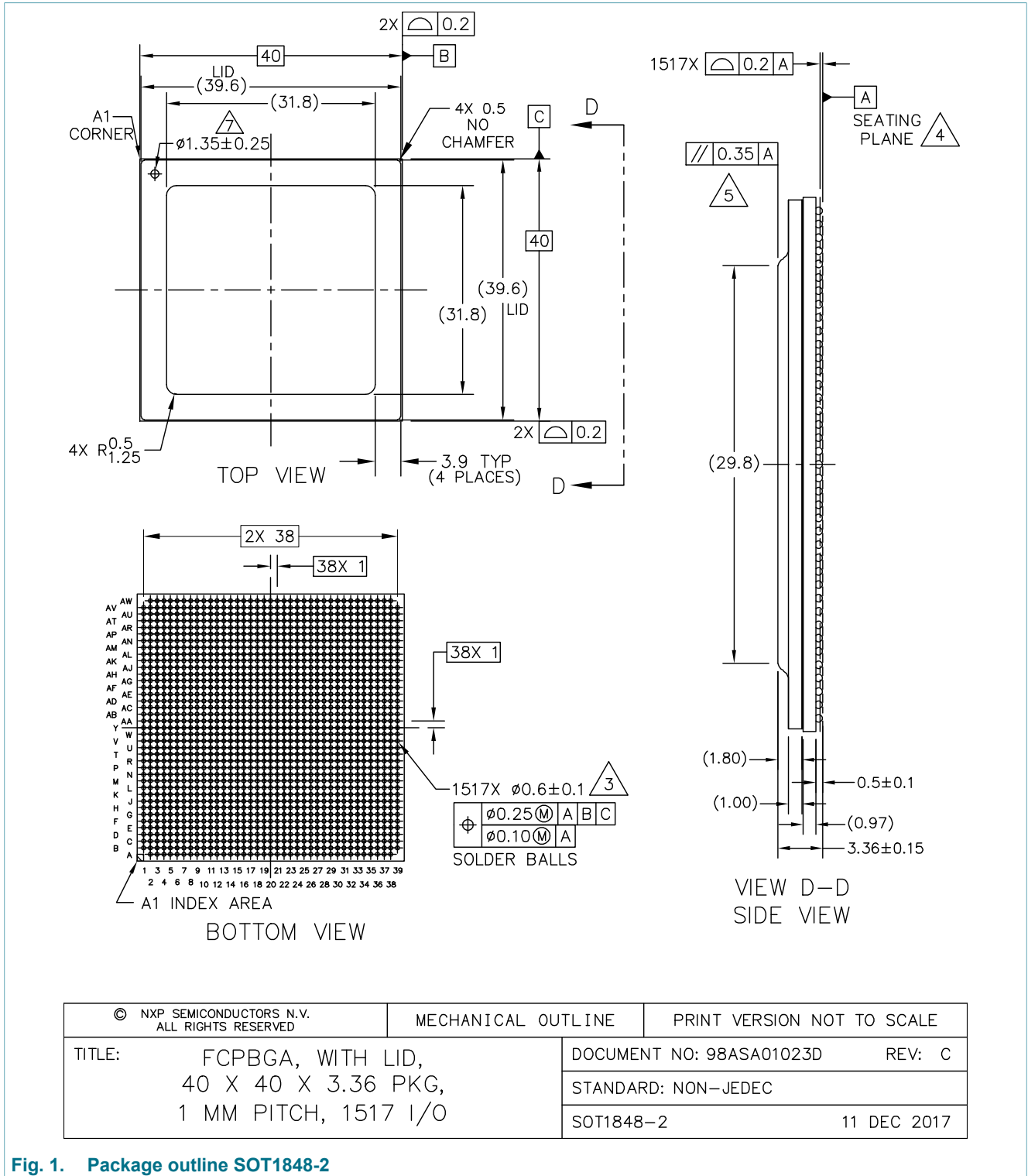


Fig. 1. Package outline SOT1848-2

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NOTES:

1. ALL DIMENSIONS IN MILLIMETERS.
2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M–1994.
3. MAXIMUM SOLDER BALL DIAMETER MEASURED PARALLEL TO DATUM A. RAW BALL DIAMETER IS 0.6MM.
4. DATUM A, THE SEATING PLANE, IS DETERMINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
5. PARALLELISM MEASUREMENT SHALL EXCLUDE ANY EFFECT OF MARK ON TOP SURFACE OF PACKAGE.
6. ALL DIMENSIONS ARE SYMMETRIC ACROSS THE PACKAGE CENTER LINES, UNLESS DIMENSIONED OTHERWISE.
7. PIN 1 THRU HOLE SHALL BE CENTERED WITHIN FOOT AREA.
8. DELETED IN REV B.
9. LID OVERHANG ON THE SUBSTRATE IS NOT ALLOWED.

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TITLE: FCPBGA, WITH LID, 40 X 40 X 3.36 PKG, 1 MM PITCH, 1517 I/O	DOCUMENT NO: 98ASA01023D	REV: C	
	STANDARD: NON–JEDEC		
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Fig. 2. Package outline note BGA1517 (SOT1848-2)

3. Legal information

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